

CLAIMS

1. A method for transferring at least one pattern in the form of a structure from a pressing means to a deformable layer (4, 21) which is arranged on a planar surface of a substrate (5), characterized in that it comprises the steps of

connecting a power source (26) over the pressing means (1),

arranging the pressing means (1) in contact with the layer (4, 21), the pattern facing the layer (4, 21),

operating the power source (26) so that a current is passed through the pressing means (1) and heats the pressing means and the layer (4, 21), and

pressing the pressing means (1) against the layer (4, 21) so that the pattern is transferred to the layer (4, 21).

2. A method as claimed in claim 1, wherein the power source is connected so that the current density in the pressing means (1) is homogeneous.

3. A method as claimed in claim 1 or 2, which further comprises the step of providing a pressing means (1) which is formed so that the current density in the pressing means (1) is homogeneous.

4. A method as claimed in any one of the preceding claims, wherein the pressing means (1) has an outer periphery and a hole which defines an inner periphery, and

(continued)

(continued claim 4)

the power source is connected between the inner periphery and the outer periphery.

5. A method as claimed in claim 4, wherein the power source is connected with the aid of two connecting means, which each extend in the radial direction of the pressing means (1).

6. A method as claimed in any one of claims 1, 2 or 3, wherein the step of connecting the pressing means (1) to a power source comprises the steps of

arranging the substrate in a recess in an electrically conducting holder means (15) which has a rectangular outer shape, and

connecting the holder means (15) to the power source (26), the pressing means having electrical contact with the holder means (15) along its entire periphery, and the combination of holder means (15) and pressing means (1) having the same electrical properties as a rectangular plate.

7. A device for transferring at least one pattern in the form of a structure (3) from a pressing means (1) to a deformable layer (4, 21) which is arranged on a planar surface of a plate-shaped substrate (5), comprising

a first holder means (2, 25), and

a second holder means (6, 24) for receiving one of the substrate and the pressing means (1) each, the device being arranged to apply a pressure between the first

(continued)

(continued claim 7)

holder means (2, 25) and the second holder means (6, 24), characterized in that it further comprises a power source for heating the pressing means, and electrical connecting means for connecting the pressing means to the power source (26).

8. A device as claimed in claim 7, wherein the pressing means has an inner periphery and an outer periphery, and the power source is connected between the inner periphery and the outer periphery.

9. A method as claimed in claim 8, wherein the thickness of the pressing means decreases with an increasing distance from the inner periphery.

10. A device as claimed in claim 7, wherein the first holder means comprises a rectangular portion (15) with a recess which is formed to receive the pressing means (16), which portion is connected on two opposed sides to the electrical connecting means (13, 14) and has the same resistivity as the substrate and which portion together with the pressing means forms a unit with the same electrical properties as a rectangular plate without a recess.

11. A device as claimed in any one of claims 7-10, wherein the pressing means is resiliently connected to the power source.

12. A device as claimed in any one of claims 7-10, wherein the pressing means is in moving contact with the

(continued)

(continued claim 12)

connecting means to enable the pressing means to slide in relation to the connecting means.